

Abstract of the Disclosure

The invention of the present application provides a heat radiation structure of a semiconductor device, comprising a substrate having, on a surface thereof, a first area on which the semiconductor device is mounted, and a second area which surrounds the first area, and the semiconductor device which has a first surface and a second surface opposite to the first surface and is formed with a plurality of terminals provided on the first surface, wherein the semiconductor device is mounted on the substrate in such a manner that the first surface is opposite to the surface of the substrate, and wherein a first heat radiating film is formed on the second area of the substrate, and a second heat radiating film is formed on the second surface of the semiconductor device with being spaced away from the first heat radiating film.